

Single N-Channel MOSFET

■ DESCRIPTION

SMC6282E is the N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced trench technology devices are well suited for high efficiency fast switching applications, low in-line power loss needed in small outline surface mount package.

■ PART NUMBER INFORMATION

SMC 6282 E SN - TR G

a	b	c	d	e	f
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a : Company name.

b : Product Serial number.

c : ESD Protection

d : Package code SN: SOT-23

e : Handling code TR: Tape&Reel

f : Green produce code G: *RoHS Compliant*

■ FEATURES

$V_{DS} = 60V, \quad I_D = 0.43A$

$R_{DS(ON)}=1.0\Omega(\text{Typ.}) @ V_{GS}=10V$

$R_{DS(ON)}=1.3\Omega(\text{Typ.}) @ V_{GS}=4.5V$

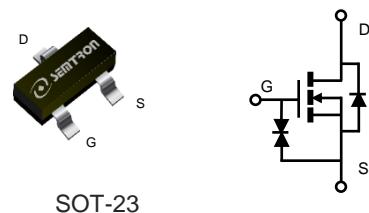
◆Fast switch

◆ESD Protection

■ APPLICATIONS

◆Hand-Held Instruments

◆Analog Switching Application.



■ ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ Unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DSS}	Drain-Source Voltage	60	V
V_{GSS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current $T_A=25^\circ\text{C}$	0.43	A
		$T_A=70^\circ\text{C}$	A
I_{DM}	Pulsed Drain Current ^A	1.2	A
P_D	Power Dissipation ^B $T_A=25^\circ\text{C}$	0.51	W
		$T_A=70^\circ\text{C}$	W
T_J	Operation Junction Temperature	-55/150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55/150	$^\circ\text{C}$

■ THERMAL RESISTANCE

Symbol	Parameter	Typ	Max	Units
$R_{\theta JA}$	Thermal Resistance Junction to Ambient ^{BC}	$t \leq 10\text{s}$	245	$^\circ\text{C}/\text{W}$
		Steady-State	350	

ELECTRICAL CHARACTERISTICS($T_A = 25^\circ\text{C}$ Unless otherwise noted)

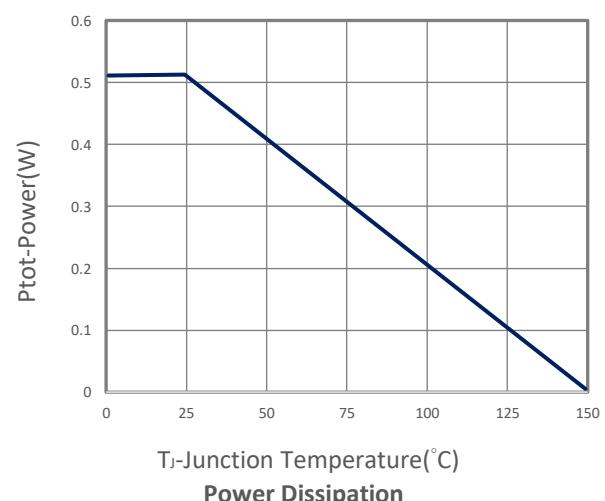
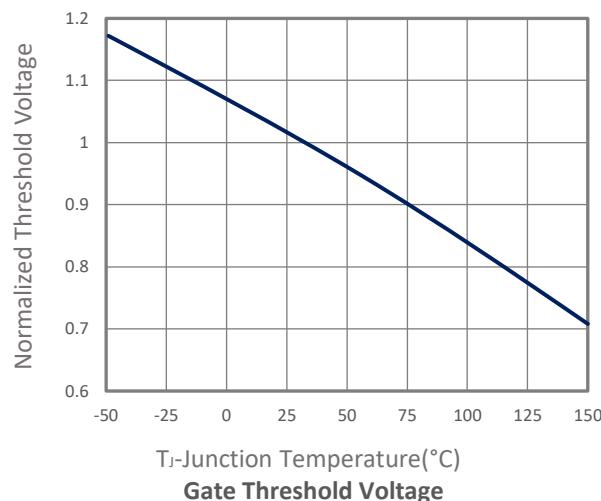
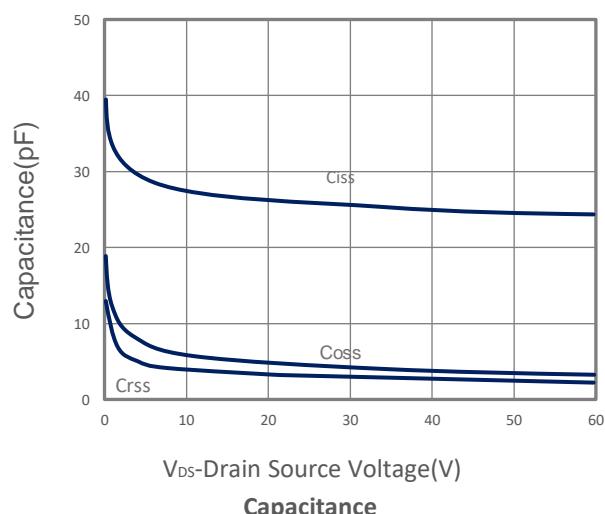
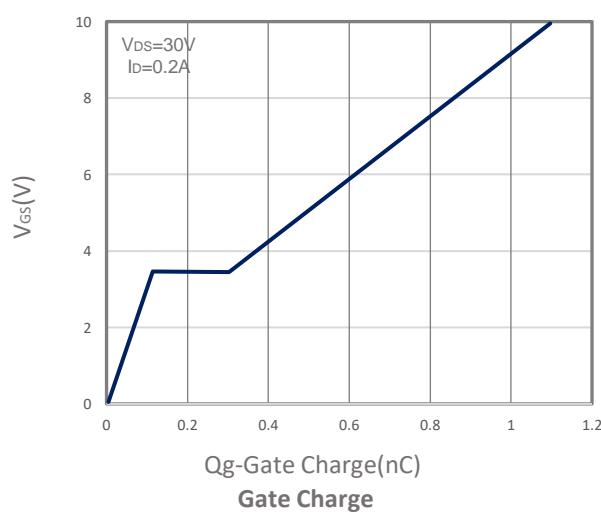
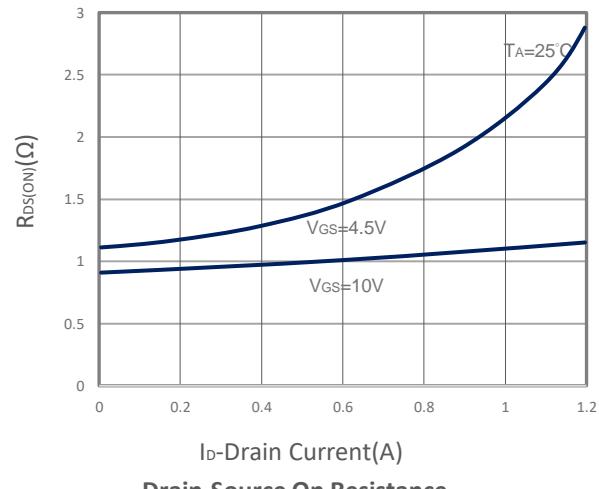
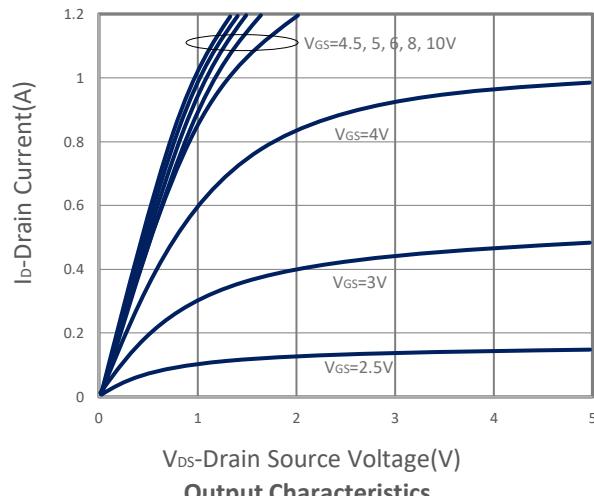
Symbol	Parameter	Condition	Min	Typ	Max	Unit	
Static Parameters							
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	60			V	
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=250\mu\text{A}$	1	1.6	2.5	V	
I_{GSS}	Gate Leakage Current	$V_{DS}=0\text{V}$, $V_{GS}=\pm 20\text{V}$			± 10	μA	
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=60\text{V}$, $V_{GS}=0\text{V}$, $T_J=25^\circ\text{C}$			1	μA	
		$V_{DS}=48\text{V}$, $V_{GS}=0\text{V}$, $T_J=75^\circ\text{C}$			10		
$R_{DS(\text{ON})}$	Drain-source On-Resistance	$V_{GS}=10\text{V}$, $I_D=0.5\text{A}$ $V_{GS}=4.5\text{V}$, $I_D=0.2\text{A}$		1 1.3	1.5 2	Ω	
Diode Characteristics							
V_{SD}	Diode Forward Voltage	$I_S=1\text{A}$, $V_{GS}=0\text{V}$			1	V	
I_S	Continuous Source Current				0.5	A	
Dynamic and Switching Parameters							
Q_g	Total Gate Charge	$V_{DS}=30\text{V}$, $V_{GS}=10\text{V}$, $I_D=0.2\text{A}$		1.1		nC	
Q_{gs}	Gate-Source Charge			0.1			
Q_{gd}	Gate-Drain Charge			0.2			
C_{iss}	Input Capacitance	$V_{DS}=10\text{V}$, $V_{GS}=0\text{V}$, $f=1\text{MHz}$		27		pF	
C_{oss}	Output Capacitance			5.8			
C_{rss}	Reverse Transfer Capacitance			3			
$t_{d(on)}$	Turn-On Time	$V_{DD}=30\text{V}$, $V_{GEN}=10\text{V}$, $R_G=10\Omega$, $I_D=0.2\text{A}$		2.95	6	nS	
t_r				4	8		
$t_{d(off)}$	Turn-Off Time			11	21		
t_f				8	15		

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged.

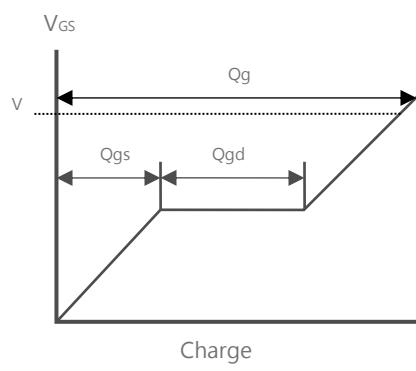
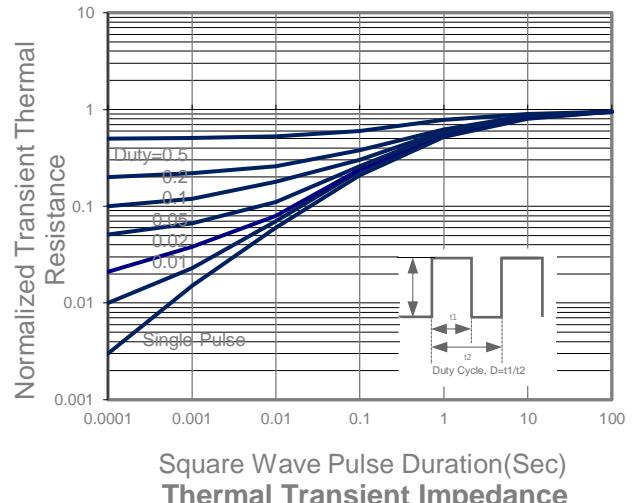
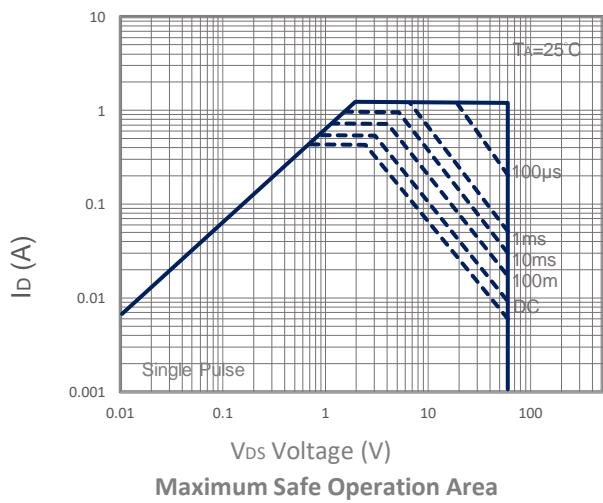
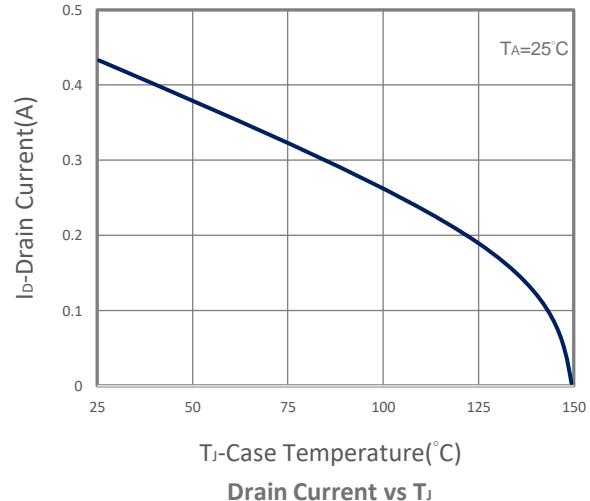
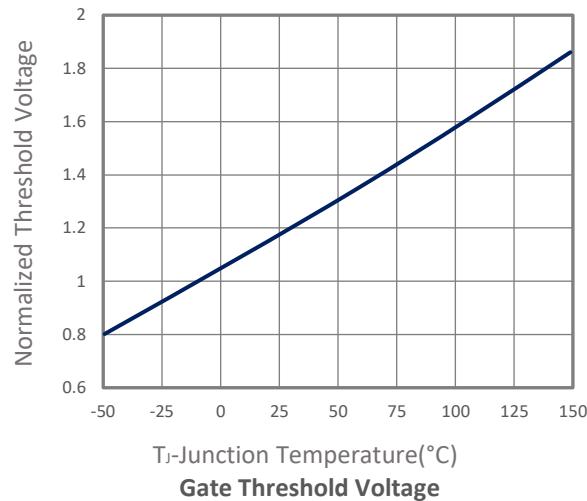
- A. Pulsed width limited by maximum junction temperature, $T_J(\text{MAX})=150^\circ\text{C}$.
- B. The value of $R_{\theta JA}$ is measured with the device mounted on 1in2 FR-4 board in a still air environment with maximum junction temperature $T_J(\text{MAX})=150^\circ\text{C}$ (initial temperature $T_A=25^\circ\text{C}$).
- C. $T_J(\text{MAX})=150^\circ\text{C}$, using junction-to-case thermal resistance ($R_{\theta JC}$) is more useful in additional heat sinking is used.

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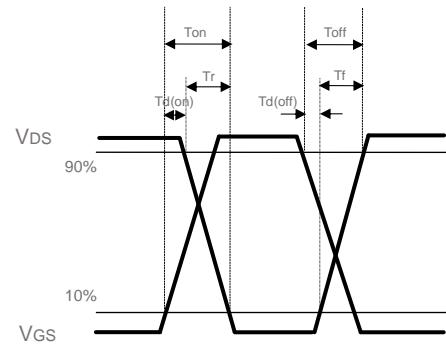
TYPICAL CHARACTERISTICS



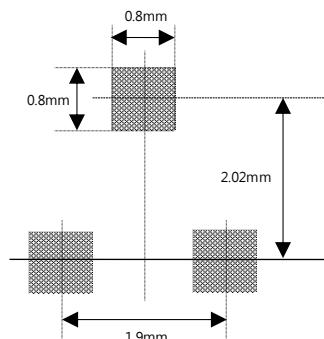
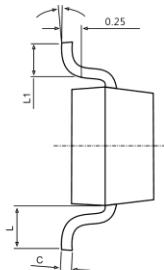
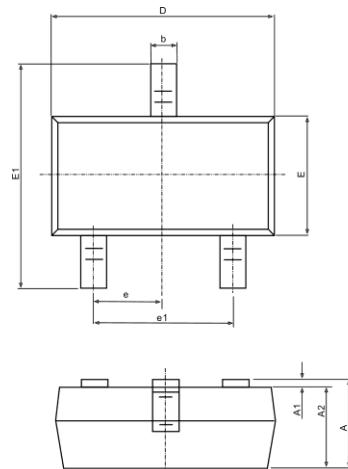
TYPICAL CHARACTERISTICS



Gate Chrgre Waveform



Switching Time Waveform

SOT-23 PACKAGE DIMENSIONS


Recommended Land Pattern

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°